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First ICTP Regional Microelectronics Workshop and Training on VHDL for Hardware Synthesis and FPGA Design in Asia-Pacific

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The CMOS inverter.

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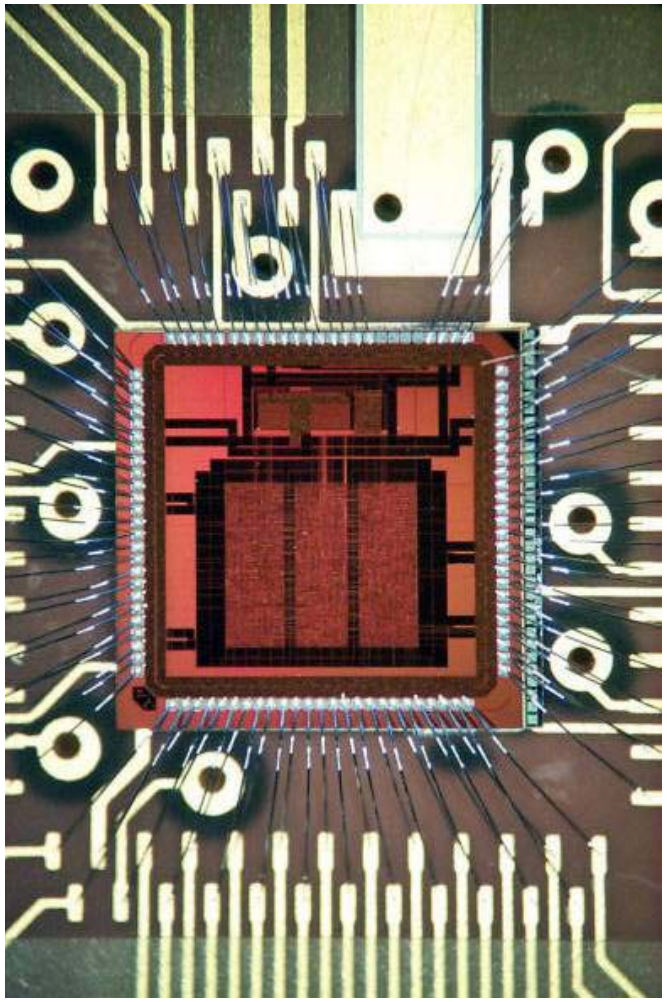
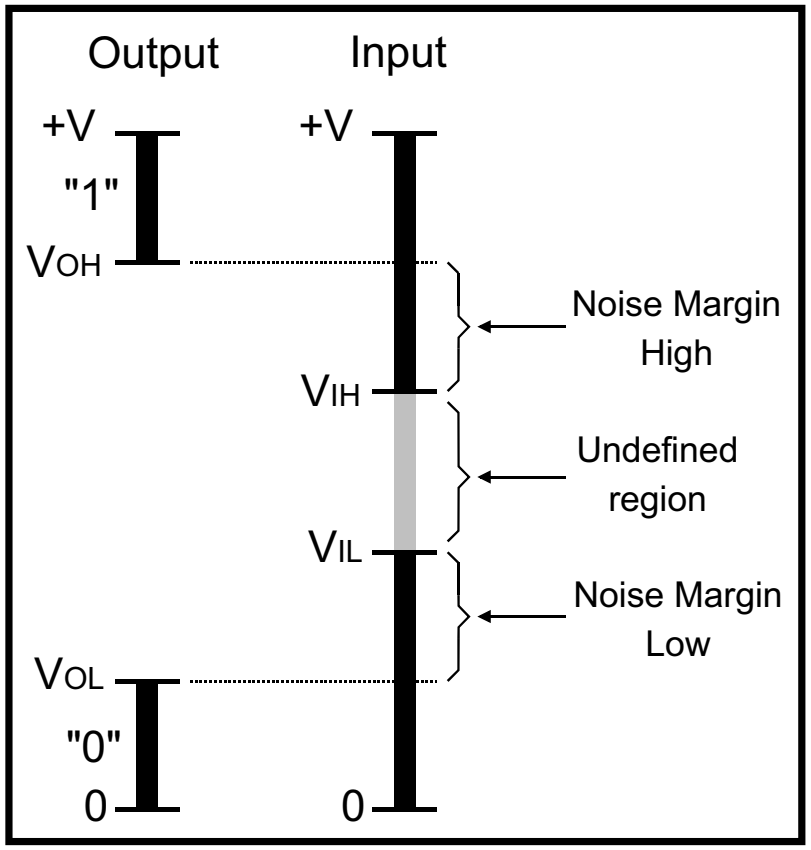
Outline

- Introduction
- Transistors
- The CMOS inverter
  - DC operation
  - Dynamic operation
    - Propagation delay
    - Power consumption
  - Layout
- Technology
- Scaling
- Gates
- Sequential circuits
- Storage elements
- Phase-Locked Loops
- Example



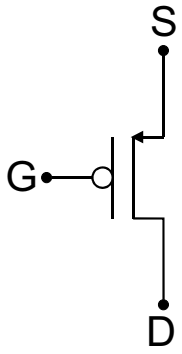
CMOS logic: "0" and "1"

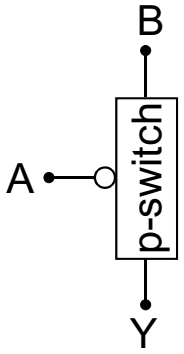
- Logic circuits process Boolean variables
- Logic values are associated with voltage levels:
  - $V_{IN} > V_{IH} \Rightarrow$ "1"
  - $V_{IN} < V_{IL} \Rightarrow$ "0"
- Noise margin:
  - $NM_H = V_{OH} - V_{IH}$
  - $NM_L = V_{IL} - V_{OL}$



The MOST - a simple switch

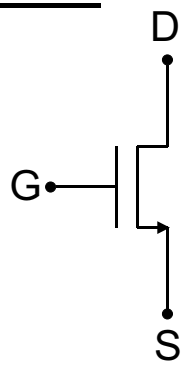
p-switch

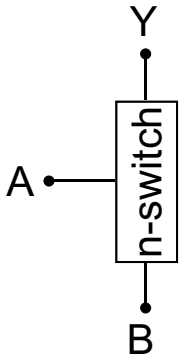




A	B	Y	
0	0	bad 0	(source follower)
0	1	**good 1**	
1	0	?	(high Z)
1	1	?	(high Z)

n-switch





A	B	Y	
0	0	?	(high Z)
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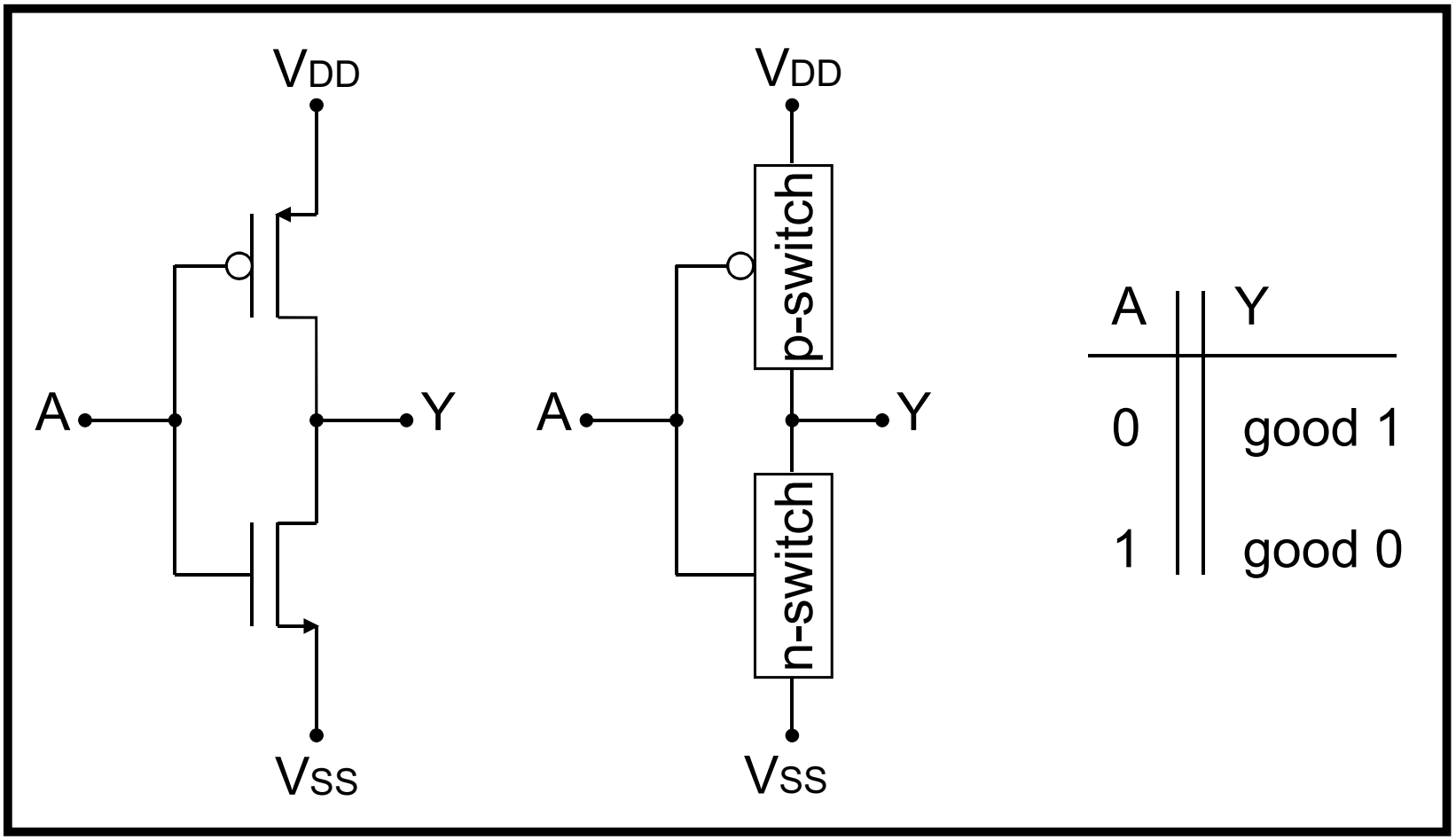
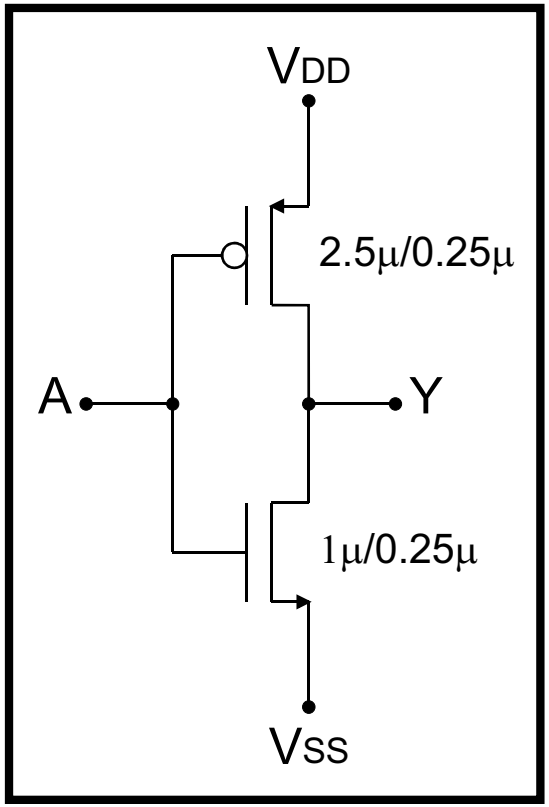
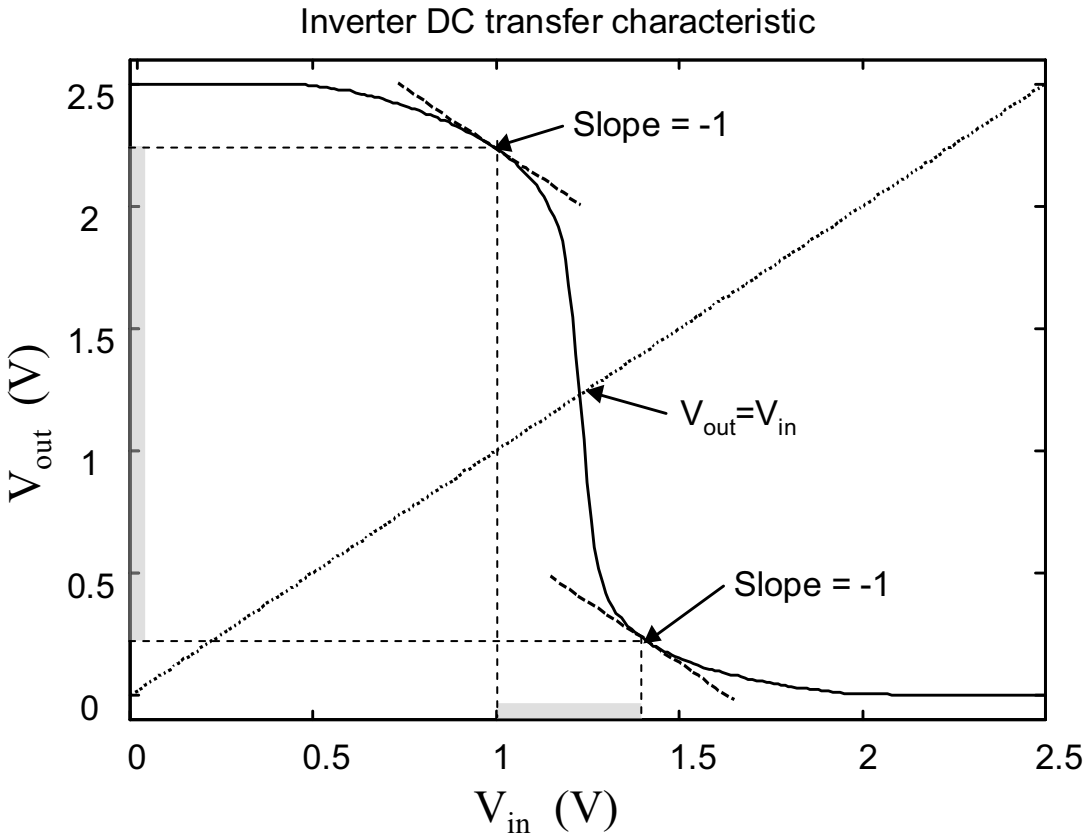
1	0	**good 0**	
1	1	bad 1	(source follower)

The CMOS inverter



DC operation



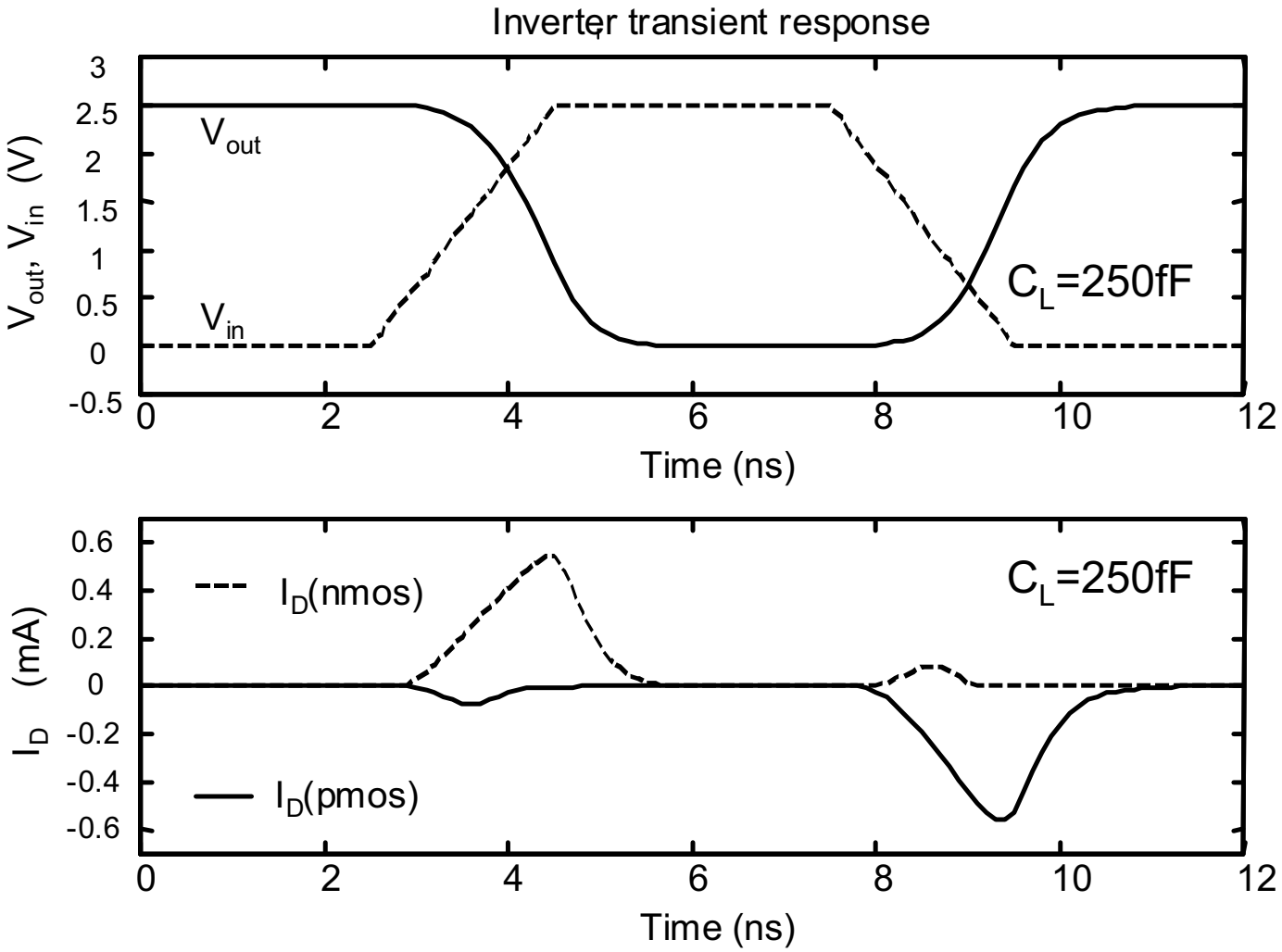


DC operation

Regions of operation (balanced inverter):

V_{in}	n-MOS	p-MOS	V_{out}
0	cut-off	linear	V_{dd}
$V_{TN}<V_{in}<V_{dd}/2$	saturation	linear	$\sim V_{dd}$
$V_{dd}/2$	saturation	saturation	$V_{dd}/2$
$V_{dd}-\|V_{TP}\|>V_{in}>V_{dd}/2$	linear	saturation	~0
V_{dd}	linear	cut-off	0

Dynamic operation



Dynamic operation

- Propagation delay
  - Main origin: load capacitance

$$t_{pLH} = \frac{C_L \cdot L_p \cdot V_{dd}}{\mu_p \cdot C_{ox} \cdot W_p \cdot \left(V_{dd} - |V_{TP}|\right)^2} \approx \frac{C_L}{k_p \cdot V_{dd}}$$

$$t_{pHL} = \frac{C_L \cdot L_n \cdot V_{dd}}{\mu_n \cdot C_{ox} \cdot W_n \cdot \left(V_{dd} - |V_{TN}|\right)^2} \approx \frac{C_L}{k_n \cdot V_{dd}}$$

$$t_p \approx \frac{1}{2}\left(t_{pLH} + t_{pLH}\right) = \frac{C_L}{2 \cdot V_{dd}}\left(\frac{1}{k_n} + \frac{1}{k_p}\right)$$

  - To reduce the delay:
    - Reduce C_L
    - Increase k_n and k_p. That is, increase W/L

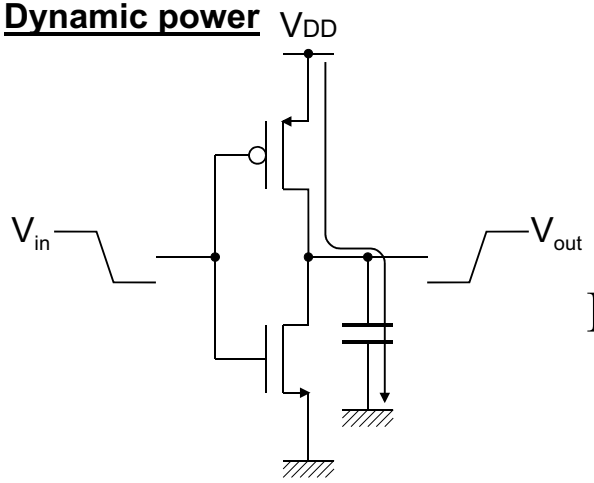
Dynamic operation

- CMOS power budget:
  - Dynamic power consumption:
    - Charging and discharging of capacitors
  - Short circuit currents:
    - Short circuit path between power rails during switching
  - Leakage
    - Leaking diodes and transistors

Dynamic operation

- The dynamic power dissipation is a function of:
  - Frequency
  - Capacitive loading
  - Voltage swing
- To reduce dynamic power dissipation
  - Reduce: C_L
  - Reduce: f
  - Reduce: V_{dd} ⇐ The most effective action

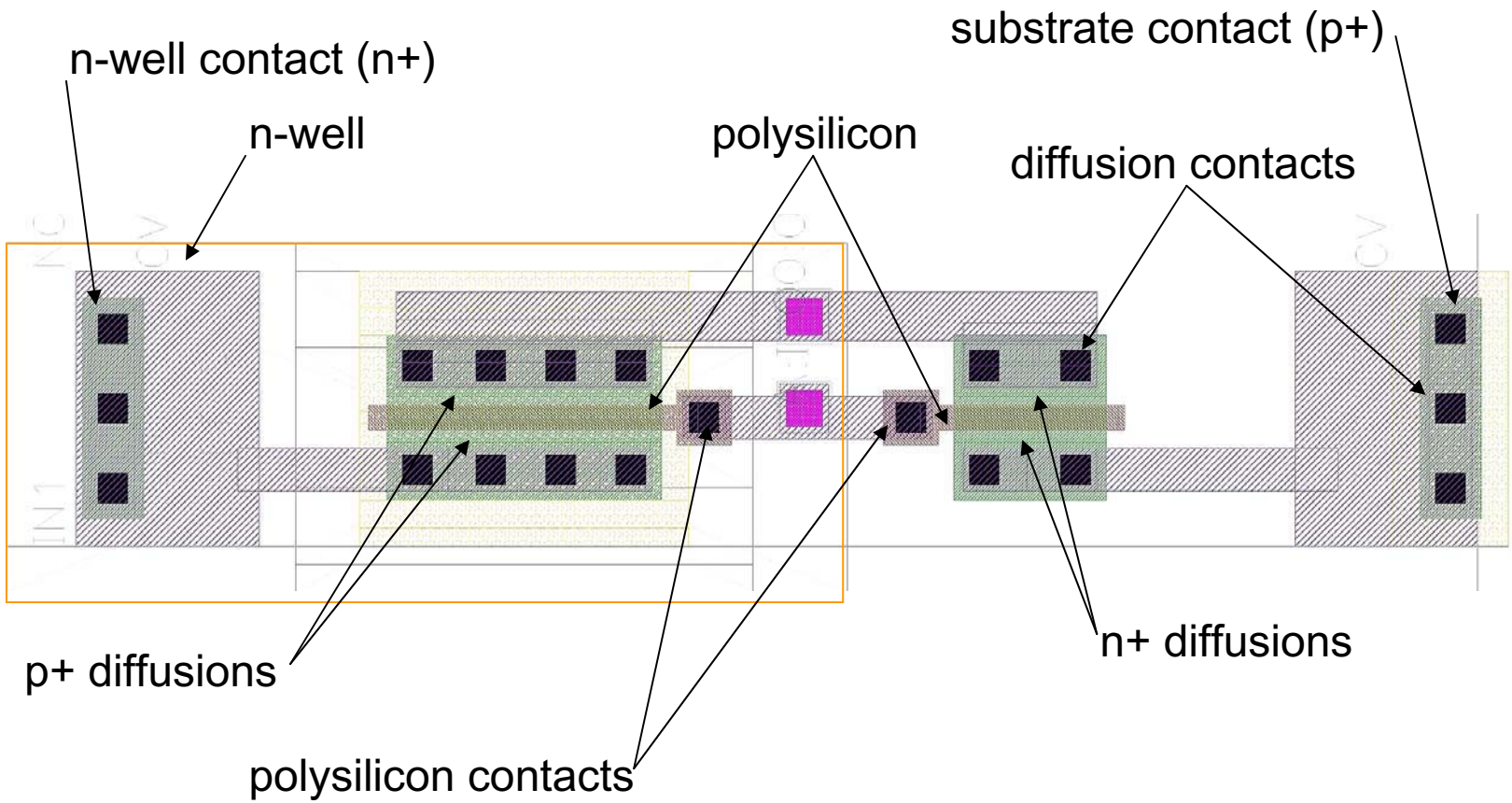
Dynamic power



$$\mathrm{E} = \text{Energy / transition} = \frac{1}{2} \cdot C_L \cdot V_{dd}^2$$

$$\mathrm{P} = \text{Power} = 2 \cdot f \cdot E = f \cdot C_L \cdot V_{dd}^2$$

Layout


n-well contact (n+)
n-well
polysilicon
substrate contact (p+)
diffusion contacts
p+ diffusions
polysilicon contacts
n+ diffusions